



PMV37EN

30 V, 3.1 A N-channel Trench MOSFET

Rev. 1 — 9 May 2011

Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

1.2 Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology

1.3 Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$	-	-	30	V
V_{GS}	gate-source voltage		-20	-	20	V
I_D	drain current	$V_{GS} = 10 \text{ V}; T_{amb} = 25^\circ\text{C}$	[1]	-	-	A
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 3.1 \text{ A}; T_j = 25^\circ\text{C}$	-	28	36	$\text{m}\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	S	source		
3	D	drain		
 SOT23 (TO-236AB)				

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3. Ordering information

Table 3. Ordering information

Type number	Package	Description	Version
Name			
PMV37EN	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMV37EN	KX%

[1] % = placeholder for manufacturing site code

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$	-	30	V
V_{GS}	gate-source voltage		-20	20	V
I_D	drain current	$V_{GS} = 10 \text{ V}; T_{amb} = 25^\circ\text{C}$	^[1]	-	3.1 A
		$V_{GS} = 10 \text{ V}; T_{amb} = 100^\circ\text{C}$	^[1]	-	1.9 A
I_{DM}	peak drain current	$T_{amb} = 25^\circ\text{C}$; single pulse; $t_p \leq 10 \mu\text{s}$	-	12.4	A
P_{tot}	total power dissipation	$T_{amb} = 25^\circ\text{C}$	^[2]	-	mW
		$T_{sp} = 25^\circ\text{C}$	^[1]	-	520 mW
			-	1800	mW
T_j	junction temperature		-55	150	°C
T_{amb}	ambient temperature		-55	150	°C
T_{stg}	storage temperature		-65	150	°C
Source-drain diode					
I_S	source current	$T_{amb} = 25^\circ\text{C}$	^[1]	-	0.6 A

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

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6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	30	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = 250 \mu\text{A}; V_{DS} = V_{GS}; T_j = 25^\circ\text{C}$	1	1.5	2.5	V
I_{DSS}	drain leakage current	$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	-	-	1	μA
		$V_{DS} = 30 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150^\circ\text{C}$	-	-	10	μA
I_{GSS}	gate leakage current	$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	-	-	100	nA
		$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	-	-	100	nA
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 3.1 \text{ A}; T_j = 25^\circ\text{C}$	-	28	36	$\text{m}\Omega$
		$V_{GS} = 10 \text{ V}; I_D = 3.1 \text{ A}; T_j = 150^\circ\text{C}$	-	45	55	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}; I_D = 2.7 \text{ A}; T_j = 25^\circ\text{C}$	-	37	47	$\text{m}\Omega$
g_{fs}	forward transconductance	$V_{DS} = 5 \text{ V}; I_D = 3 \text{ A}; T_j = 25^\circ\text{C}$	-	10	-	S
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$V_{DS} = 15 \text{ V}; I_D = 3 \text{ A}; V_{GS} = 10 \text{ V}; T_j = 25^\circ\text{C}$	-	6.5	10	nC
Q_{GS}	gate-source charge		-	1	-	nC
Q_{GD}	gate-drain charge		-	1	-	nC
C_{iss}	input capacitance	$V_{DS} = 15 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	-	330	-	pF
C_{oss}	output capacitance		-	76	-	pF
C_{rss}	reverse transfer capacitance		-	36	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 15 \text{ V}; V_{GS} = 10 \text{ V}; R_{G(ext)} = 6 \Omega; T_j = 25^\circ\text{C}; I_D = 3 \text{ A}$	-	4	-	ns
t_r	rise time		-	14	-	ns
$t_{d(off)}$	turn-off delay time		-	55	-	ns
t_f	fall time		-	23	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 0.6 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	-	0.75	1.2	V